L Number	Hits	Search Text	DB	Time stamp
-	28022	etchant or "etching gas"	USPAT;	2002/12/17 18:10
			US-PGPUB	
-	145	(adsorb\$3 or adsorption or condens\$3 or condensation) with	USPAT;	2002/12/17 21:18
		(etchant or "etching gas")	US-PGPUB	2002/12/17 21:10
-	994349	water	USPAT; US-PGPUB	2002/12/17 21:18
	24066	and water	USPAT;	2002/12/17 21:18
-	21966	ozone and water	US-PGPUB	2002/12/17 21:10
_	10405	(adsorb\$3 or adsorption or condens\$3 or condensation) and	USPAT;	2002/12/17 21:19
-	10 103	(ozone and water)	US-PGPUB	
-	215	(etchant or "etching gas") and ((adsorb\$3 or adsorption or	USPAT;	2002/12/17 21:19
		condens\$3 or condensation) and (ozone and water))	US-PGPUB	
-	553830	semiconductor or "integrated circuit" or silicon	USPAT;	2002/12/17 21:20
			US-PGPUB	2002/42/47 24-21
-	3533	((adsorb\$3 or adsorption or condens\$3 or condensation)	USPAT; US-PGPUB	2002/12/17 21:21
		and (ozone and water)) and (semiconductor or "integrated	U3-PGPUB	
	200	circuit" or silicon) (adsorb\$3 or adsorption or condens\$3 or condensation) with	USPAT:	2002/12/17 21:21
-	200	ozone with water	US-PGPUB	
_	15	(US-6337277-\$ or US-6099945-\$ or US-6024888-\$ or	USPAT;	2002/12/18 12:25
		US-5935454-\$ or US-5500079-\$ or US-5354416-\$ or	US-PGPUB	
		US-5087323-\$ or US-5030319-\$ or US-6299696-\$).did. or	1	1
		(US-20020177323-\$ or US-20020121502-\$ or	1	
		US-20020038681-\$ or US-20010006849-\$ or		
		US-20020134409-\$ or US-20020122753-\$).did.		2002/42/40 42 20
•	490771	wafer or substrate	USPAT; US-PGPUB	2002/12/18 12:26
	700153	cool\$3	USPAT;	2002/12/18 12:26
•	700133	COOI\$3	US-PGPUB	2002/12/10 12:20
	22000	(wafer or substrate) with cool\$3	USPAT;	2002/12/18 12:27
	22000	(Marai di danda ana) mana asanja	US-PGPUB	1 ' '
	29628	ozone	USPAT;	2002/12/18 12:27
			US-PGPUB	
-	828	((wafer or substrate) with cool\$3) and ozone	USPAT;	2002/12/18 12:27
		- 1	US-PGPUB	2002/12/10 12:20
-	347653	@ad>20000523 @rlad>20000523	USPAT; US-PGPUB	2002/12/18 12:28
	649	(((wafer or substrate) with cool\$3) and ozone) not	USPAT;	2002/12/18 12:28
-	043	((Wades of Substrate) with Cool\$3) and George not	US-PGPUB	2002/12/10 12:20
	1021500	water or steam	USPAT;	2002/12/18 12:29
	1021000	Track of Steam	US-PGPUB	
-	486	((((wafer or substrate) with cool\$3) and ozone) not	USPAT;	2002/12/18 12:29
		(@ad>20000523 @rlad>20000523)) and (water or steam)	US-PGPUB	
-	392087	adsorb\$3 or adsorption or condens\$3 or condensation	USPAT;	2002/12/18 12:30
	200	//// -f b-b-b-> with society and ones ->	US-PGPUB USPAT:	2002/12/18 12:30
-	289	((((((wafer or substrate) with cool\$3) and ozone) not	US-PGPUB	2002/12/16 12:30
		(@ad>20000523 @rlad>20000523)) and (water or steam)) and (adsorb\$3 or adsorption or condens\$3 or condensation)	U3-FGFUB	
_	52	(semiconductor or "integrated circuit" or silicon) and	USPAT:	2002/12/18 15:18
	32	((adsorb\$3 or adsorption or condens\$3 or condensation)	US-PGPUB	
		with ozone with water)		
-	288	((((((wafer or substrate) with cool\$3) and ozone) not	USPAT;	2002/12/18 12:31
		(@ad>20000523 @rlad>20000523)) and (water or steam))	US-PGPUB	1
		and (adsorb\$3 or adsorption or condens\$3 or	1	1
		condensation)) not ((semiconductor or "integrated circuit" or	1	1.5
		silicon) and ((adsorb\$3 or adsorption or condens\$3 or		1
_	35	condensation) with ozone with water)) (semiconductor or "integrated circuit" or silicon) and	EPO; JPO;	2002/12/18 15:19
	33	((adsorb\$3 or adsorption or condens\$3 or condensation)	DERWENT;	2002/12/10 10:10

•	12	(semiconductor or "integrated circuit" or silicon) and	EPO; JPO;	2002/12/18 15:22
		((adsorb\$3 or adsorption or condens\$3 or condensation)	DERWENT;	
		with ozone with water)	IBM_TDB	
	23	((semiconductor or "integrated circuit" or silicon) and	EPO; JPO;	2002/12/18 15:22
)	((adsorb\$3 or adsorption or condens\$3 or condensation)	DERWENT;	
	-	and ozone and water)) not ((semiconductor or "integrated	IBM_TDB	
	1	circuit" or silicon) and ((adsorb\$3 or adsorption or	}	
	1	condens\$3 or condensation) with ozone with water))		
	71	(US-6337277-\$ or US-6099945-\$ or US-6024888-\$ or	USPAT;	2002/12/18 17:38
	1	US-5935454-\$ or US-5500079-\$ or US-5354416-\$ or	US-PGPUB;	
	1	US-5087323-\$ or US-5030319-\$ or US-6299696-\$ or	DERWENT	
	[US-6432845-\$ or US-6429493-\$ or US-6403498-\$ or	1	
	j	US-6368891-\$ or US-6358830-\$ or US-6350685-\$ or	j	
	Ì	US-6340435-\$ or US-6284205-\$ or US-6281141-\$ or	1	
		US-6246105-\$ or US-6245659-\$ or US-6239041-\$ or		
		US-6238511-\$ or US-6232156-\$ or US-6194304-\$ or	1	l .
		US-6184068-\$ or US-6144097-\$).did. or (US-6143081-\$ or	1	1
		US-6107182-\$ or US-5967156-\$ or US-5962194-\$ or		
		US-5953634-\$ or US-5925577-\$ or US-5923962-\$ or	Ì	
		US-5904770-\$ or US-5843833-\$ or US-5840600-\$ or	1	1
	1	US-5714306-\$ or US-5643826-\$ or US-5078832-\$ or	1	
		US-4911103-\$ or US-4910043-\$ or US-4906328-\$ or)	Ì
		US-4891488-\$ or US-4886570-\$ or US-4877757-\$ or	1	1
	1	US-4875989-\$ or US-4863558-\$ or US-4857132-\$ or	1)
		US-4855160-\$ or US-4844773-\$ or US-4842687-\$ or	1	ł
	1	US-4842676-\$ or US-4836905-\$).did. or (US-4832779-\$ or	ì	1
	1	US-4832777-\$ or US-4830705-\$ or US-4830700-\$ or	ì	ì
		US-4822450-\$ or US-4818327-\$ or US-4818326-\$ or		
	1	US-4778532-\$).did. or (US-20020177323-\$ or		
	j	US-20020121502-\$ or US-20020038681-\$ or	i	
	1	US-20010006849-\$ or US-20020134409-\$ or)	Ì
		US-20020122753-\$).did. or (JP-2001276758-\$ or		
		US-20020050279-\$ or US-20020020436-\$ or	1	
		WO-200137329-\$).did.		
	1	("6240933").PN.	USPAT;	2002/12/18 17:38
			US-PGPUB	